

Abstract

The invention relates to an apparatus and a method for applying semiconductor chips (5) to a plurality of substrates (4), in particular smartcard modules or flexboards, wherein at an adhesive application device (1) adhesive is applied to the substrate (4) at predefined substrate positions, at a fitting device (2) the substrate (4) is fitted with the semiconductor chips (5) at the substrate positions, and in a curing device (3) the adhesive is cured, wherein the curing device (3) and/or a further device can be connected by a clamping device (13, 14) to a conveyor belt (6) which transports the substrates (4) along the devices, and can be moved in the transport direction, at a transport speed of the conveyor belt (6), by a lifting device (15).

(Fig. 2)

23 MAR 2005

(19) Weltorganisation für geistiges Eigentum
Internationales Büro



(43) Internationales Veröffentlichungsdatum
15. April 2004 (15.04.2004)

PCT

(10) Internationale Veröffentlichungsnummer
WO 2004/032202 A2

(51) Internationale Patentklassifikation⁷: H01L 21/00

(21) Internationales Aktenzeichen: PCT/EP2003/010778

(22) Internationales Anmeldedatum:
27. September 2003 (27.09.2003)

(25) Einreichungssprache: Deutsch

(26) Veröffentlichungssprache: Deutsch

(30) Angaben zur Priorität:
102 45 398.5 28. September 2002 (28.09.2002) DE

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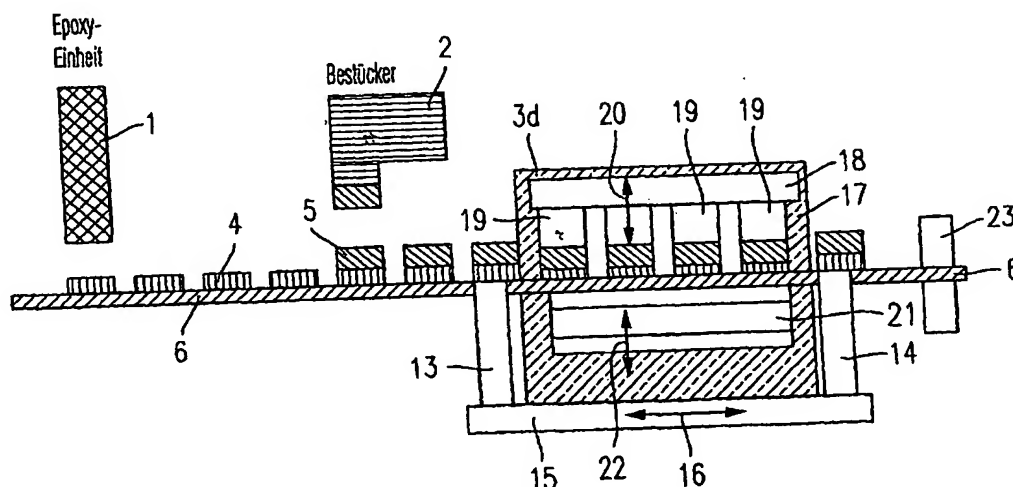
(81) Bestimmungsstaaten (*national*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Bestimmungsstaaten (*regional*): ARIPO-Patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), eurasisches Patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), europäisches Patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI-Patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

[Fortsetzung auf der nächsten Seite]

(54) Title: DEVICE AND METHOD FOR APPLYING SEMICONDUCTOR CHIPS TO CARRIERS

(54) Bezeichnung: VORRICHTUNG UND VERFAHREN ZUR AUFBRINGUNG VON HALBLEITERCHIPS AUF TRÄGERN



1... EPOXY UNIT
2... FITTING DEVICE

(57) Abstract: The invention relates to a device and a method for applying semiconductor chips (5) to a plurality of carriers (4), especially smart card modules or flexboards. According to the invention, an adhesive application device (1) is used to apply an adhesive to pre-defined positions on the carrier (4), a fitting device (2) is used to apply the semiconductor chips (5) to the positions on the carrier (4), and a hardening device (3) is used to harden the adhesive. The hardening device (3) and/or another device can be connected to a conveyor belt (6) for transporting the carrier (4) along the devices, by means of a clamping device (13, 14), and can be displaced in the transport direction at the speed of the conveyor belt (6), by means of a lifting device (15).

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